sPHENIX INTT

- Weekly Report

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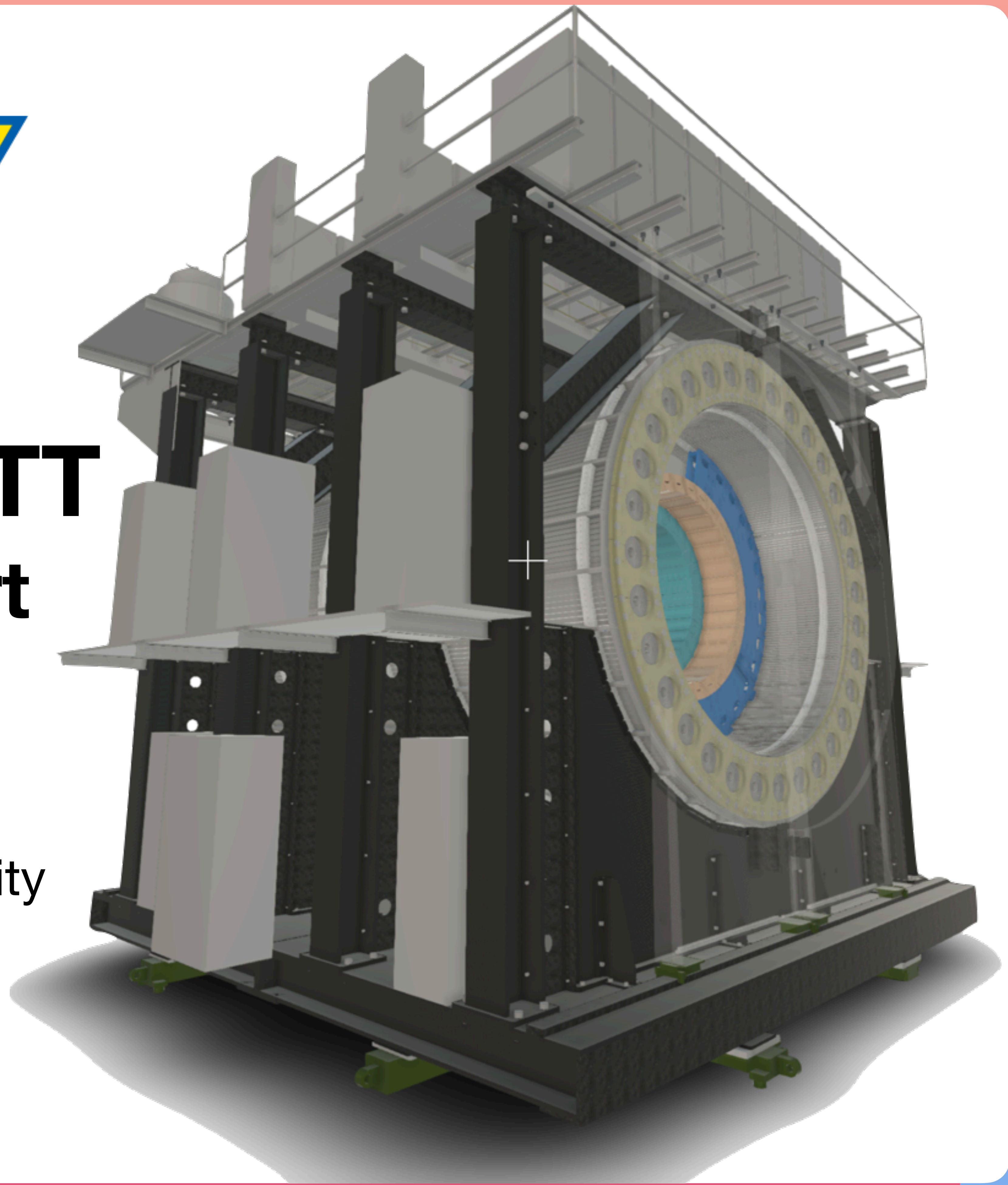
2021/10/29



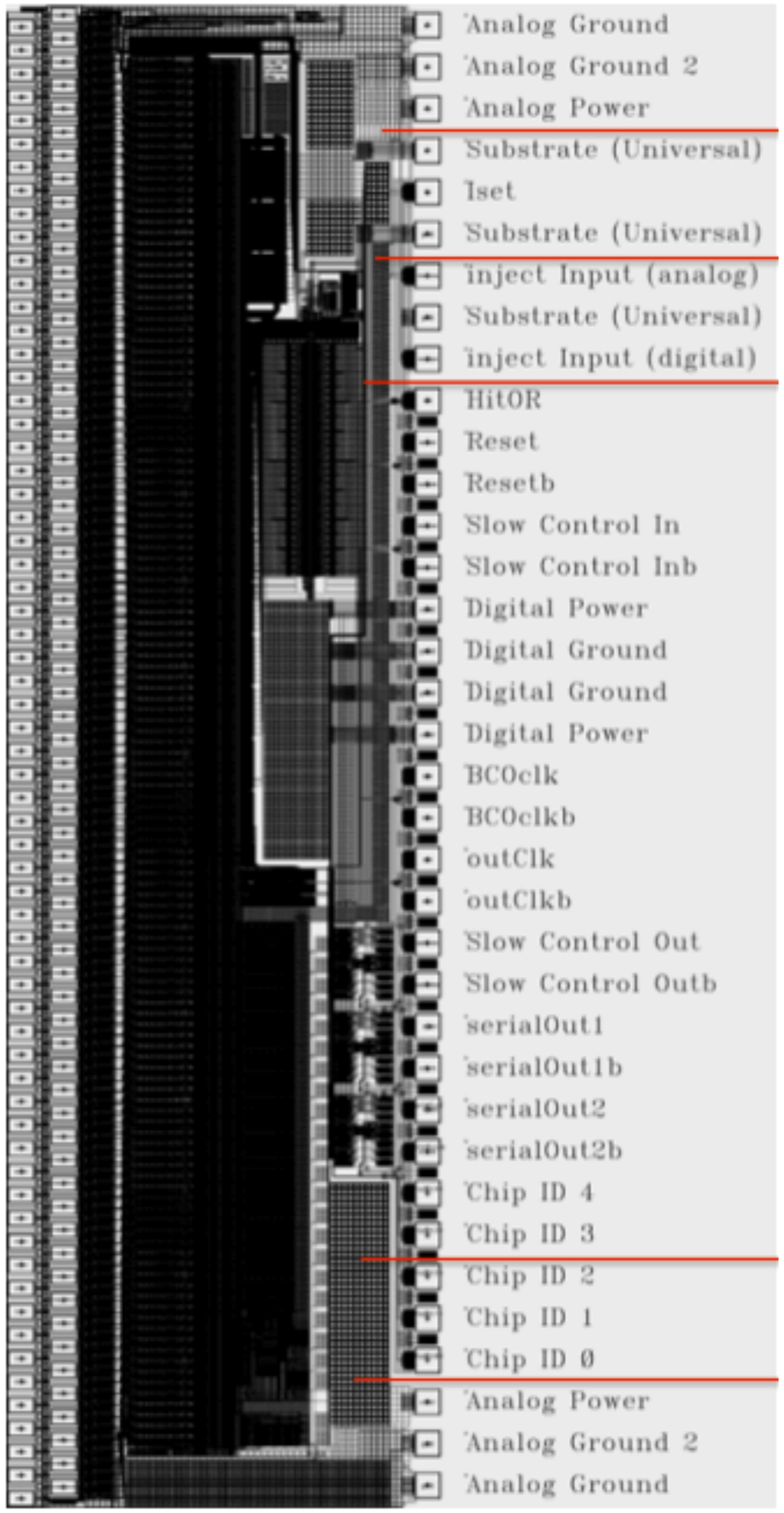
Half-ladder assembly status

Half-ladder assembly

	Total	Good	Not yet bonded & tested	Bad
Chip to HDI	20	4	2	14
Sensor to HDI	5	3	2	0
Encapsulation	3	1	2	0
Thermal cycle	6	5	0	1
On ladder	32	28	X	4

One in NWU

Half-ladder assembly status



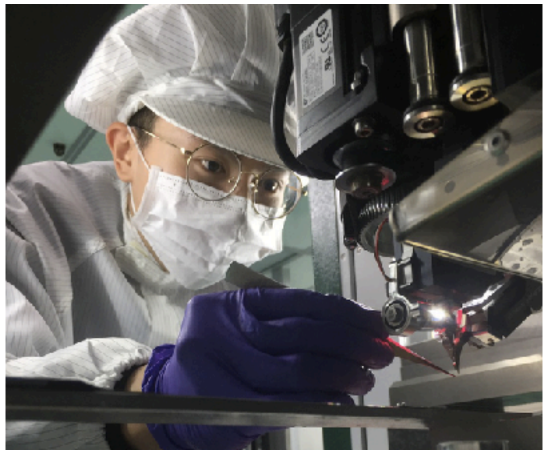
3 half-ladders have some chip -to- HDI un-bonded wires

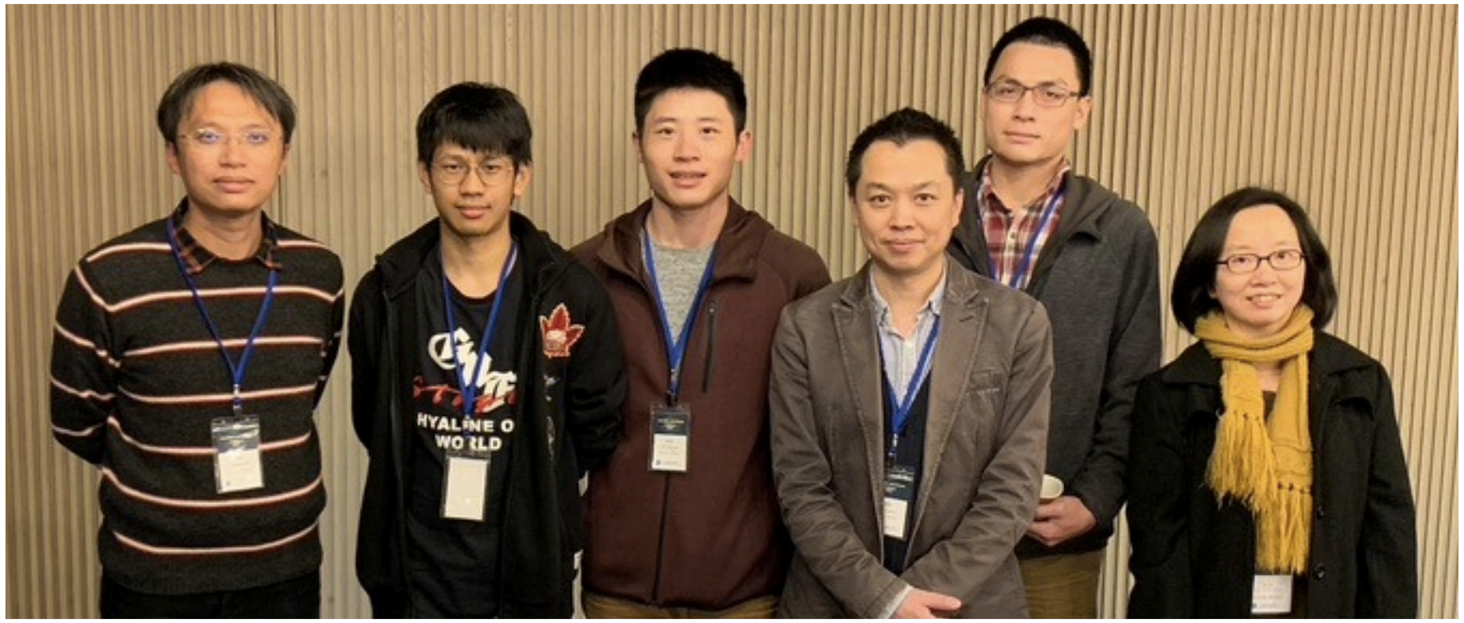
- Module 267 (2 un-bonded) :
  - U23 : inject input (digital), U21 : substrate (universal)
- Module 334 (2 un-bonded):
  - U16 : Chip ID 2, Chip ID 3
- Module 269 (7 un-bonded) :
  - U4 : inject input (digital), U12: inject input (digital)
  - U11: inject input (analog)
  - U10: Iset, substrate (Universal), inject input (analog), substrate (Universal)

The bonding parameters fine tuning was performed.
For the following 11 half-ladders, all are well bonded.

Back up

Taiwan INTT team





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